CVD Trap 시스템 내부 **Titanium Nitride** 부산물의 **CFD** 모델링

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CFD Modeling of Reaction on Titanium Nitride Byproducts in CVD Trap System

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INTRODUCTION

 Currently, as CVD surface reaction applied in semiconductor industry requires complicated chemistry, it is concerned on critical issue that the byproducts resulted from the residue gases damages the exhaust line and pumping system of CVD equipment. The Surface reaction in the exhaust line and pumping system is generally occurring in low temperature. The research on the surface reaction of high temperature has already many outcomes in terms of material science of product, but that of low temperature has rare interest and results. In terms of equipments to productivity improvement, The research on the surface reaction of low temperature is critical and meaningful works in this states of semiconductor industry.

 In current industrial steam line, TiN is essential process to make a diffusion barrier of semiconductor. Trap system located behind TiN CVD chamber has a significant rule to reduce damaging the exhaust line and pumping system because TiN byproducts (TiCl4.4NH3(s)) formed below 200℃ in Trap system.

 In this work, to understand the character of the condition and reaction product (TiCl4.4NH3(s)) in trap system, the study of computation fluid dynamics(CFD) coupled with experimental studies is used to analyze the Trap system. At low-pressure and temperature below 200°C, CVD of TiN byproducts has been achieved by experiment data¹ and modeling the chemical formation of TiN byproducts by Gaussian 98 program and Chemkin program². Of these, TiCl4.4NH3(s) is recommended to one of the main byproduct of TiN byproducts because of its thermal stability of chemical reaction.

 $TiCl_4$ (g) + 4NH₃ (g) \rightarrow TiCl₄.4NH₃(s)

EXPERIMENTAL AND CALCULATIONAL DETAILS

The trap system used in actual stream line is equipped just behind CVD chamber, shown schematically in Figure 1. After The TiN reaction products were synthesized at below 200℃ and deposited at 530°C in CVD Chamber, the residue process gases of $NH₃(60scm)$ with carrier gas of N_2 (500sccm), TiCl₄(60sccm) with carrier gas of N_2 (500sccm) and NH₃(100sccm) gas injected from bypass line make TiCl4.4NH3(s) as TiN byproduct at below 200℃. Inlet mixture gases sum up as TiCl₄ (60sccm), NH₃ (100sccm), N₂ (1000sccm), shown in Figure 1. The processing pressure of Inlet was maintained at 4.4 Torr using the throttle valve under the Trap.

Figure 1. Schematic diagram ; (a) and (b)

The temperature and the amount of $TiCl₄.4NH₃(s)$ depositions measured in experiment to compare with calculated values. The core part of Trap is Trap body because $TiCl₄.4NH₃(s)$ deposition mainly takes place in. So, the Trap body is determinant of Trap efficiency. The temperature of Trap body (Figure.1(b)) is measured with a thermocouple, changing the heating temperature of heater to three cases of 530℃/ 450℃/ 350℃.

 Model Description and Development The surface reaction is modeled using the Arrhenius model. The following reaction mechanism proposed by Brager⁵:

 $TiCl₄(g) + 4NH₃(g) \rightarrow TiCl₄.4NH₃(s)$

 The activation energy and reaction coefficient for this reaction are obtained from the experiment, plotting Arrhenius plots (figure. 2).

Figure 2. The Arrhenius plot of $TiCl₄4NH₃(s)$ deposition reaction

The experiment of The TiCl₄ 4NH₃(s) deposition rate [mg/ $\text{cm}^* \cdot \text{sec}$] of Trap body surface is measured by processing for 4hr. To accurately measure the obtained compound of TiCl₄ 4NH₃(s), electrical scale is used according to 6cm² of the Trap Surface, depending on the identified temperature of heater $(530^{\circ}\text{C}/450^{\circ}\text{C}/350^{\circ}\text{C})$. The TiCl₄ $4NH_3(s)$ deposition rate per unit area of Trap surface is calculated through the following equation,

$$
\omega_s = AT^n \exp(-E_a/RT)[TiCl_4]^{\alpha}
$$

The simulation condition of this reaction is sum up to table 1.

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preexponential constant, A (m/sec)	1.333 m/sec
temperature exponent n	
activation temperature E_a/R (K)	1207.430 K
the order of reaction (α)	

Table 1. The simulation condition of the TiCl₄[']4NH₃(s)deposition reaction

RESULTS AND DISCUSSION

 Chemical Vapor deposition of Trap system depends on a complex interaction between the diffusive and convective heat and mass transport and chemical reaction occurring in the system. The temperature at the body of Trap is shown in Figure 3 as comparing the real experimental estimation. It can be seen that the trap body at three different temperatures of heating (530℃/ 450℃/ 350℃) has certain trend of increasing the temperature of the trap body by heat transfer phenomena.

Figure 3. Temperature profile of Trap body depending on heating temperature

The TiCl₄⁴NH₃(s) deposition rates predicted by the model at different temperature and deposition pressures are further compared with the corresponding ones obtained from experiments in the CVD TRAP system used. Figure 4 (a) shows $TiCl₄4NH₃(s)$ deposition rate at body temperate of 390 - 420°C. Although the TiCl₄ 4NH₃(s) deposition rate of simulation result differ from the experimental results by 1st order, it reveals that TiCl₄4NH₃(s) deposition is critically depending on the temperature on the Trap body as meaningful results.

(a) deposition rate of simulation result (b) deposition rate of experimental result

화학공학의 이론과 응용 제13권 제1호 2007년

Figure 4. TiCl₄ $4NH₃(s)$ deposition rates of (a) simulation result and (b) experimental result

CONCLUSION

 Computational fluid dynamics is an effective method for studying CVD TRAP systems, because it enables three-dimensional representation of the system and good visualization of the physical phenomena that occur in this work on TiCl₄ 4NH₃(s) deposition from gases. CFD studies are shown to predict the velocity, temperature, and concentration profiles as well as deposition rate in the TRAP system. Simulation results indicate somewhat good agreement with experimental data obtained in the MOCVD Trap system. The effect of Trap body temperature on the $TiCl₄4NH₃(s)$ deposition are predicted satisfactorily to meaning aspect. The deposition rate is found to increase significantly with increasing Trap body temperature; this suggests the TiCl₄ 4NH₃(s) deposition is surface-reaction-controlled. In addition, the deposition kinetics model used to in the simulation is found to describe the overall Trap surface phenomena well.

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